

PRELIMINARY SPEC

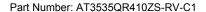


ATTENTION

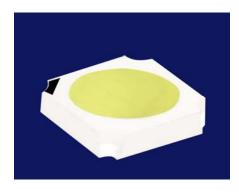
OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- 1.Dimensions: 3.5mm X 3.5mm X 0.8mm.
- 2. Higher brightness .
- 3.Small package with high efficiency .
- 4. Surface mount technology .
- 5.ESD protection .
- 6. Moisture sensitivity level: level 2a.
- 7. Soldering methods: IR reflow soldering.
- 8.RoHS compliant.



Cool White



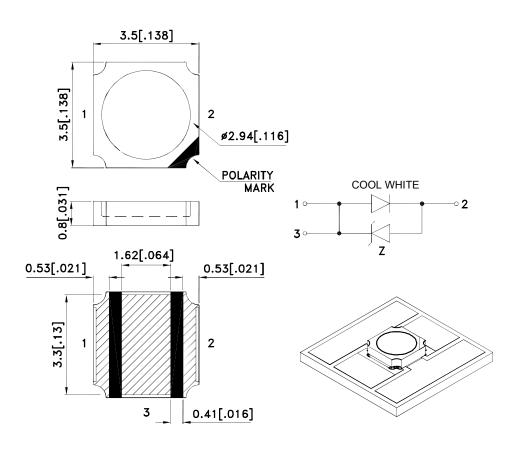
Material as follows:

Package: Ceramics

Encapsulating resin : Silicone resin

Electrodes : Ag plating

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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Selection Guide

Part No.	Dice		Viewing Angle [1]		
1 2		Code.	Min.	Max.	201/2
AT3535QR410ZS-RV-C1	Cool White (AlGalnN)	В9	42	50	
		B10	50	60	4000
		B11	60	70	120°
		B12	70	80	

Notes:

Absolute Maximum Ratings at TA = 25°C

Parameter	Symbol	Value	Unit
DC Forward Current [1]	lF	350	mA
Peak Forward Current [2]	lғм	500	mA
Power dissipation	Pt	1.25	W
Operating Temperature	Тор	-40 To +100	°C
Storage Temperature	Tstg	-40 To +120	°C
Junction temperature[1]	TJ	120	°C
Thermal resistance [1] (Junction/ambient)	Rth j-a	70	°C/W
Thermal resistance [1] (Junction/solder point)	Rth j-s	26	°C/W

Electrical / Optical Characteristics at T_A = 25°C

Parameter	Symbol	Value	Unit	
Forward Voltage IF = 350mA [Min.]		2.8		
Forward Voltage IF = 350mA [Typ.]	VF [1]	3.2	V	
Forward Voltage IF = 350mA [Max.]		3.6		
Color Temperature Ir=350mA [Min.]		5310		
Color Temperature Ir=350mA [Typ.]	ССТ	6000	К	
Color Temperature IF=350mA [Max.]		7040		
Luminous Flux IF = 350mA [Typ.]	Ф۷	60	lm	
Temperature coefficient of x IF = 350mA , $-10^{\circ}\text{C} \le \text{T} \le 100^{\circ}\text{C}$ [Typ.]	TC x	-0.15	10 ⁻³ /°C	
Temperature coefficient of y IF = 350mA , $-10^{\circ}\text{C} \le \text{T} \le 100^{\circ}\text{C}$ [Typ.]	ТСу	-0.13	10 ⁻³ /°C	
Temperature coefficient of VF IF = 350mA , - $10^{\circ}\text{C} \le \text{T} \le 100^{\circ}\text{C}$ [Typ.]	TCv	-3.2	mV/°C	

Note:

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^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity / luminous flux: +/-15%.

^{1.} Results from mounting on metal core PCB, mounted on pc board-metal core PCB is recommend for lowest thermal resistance.

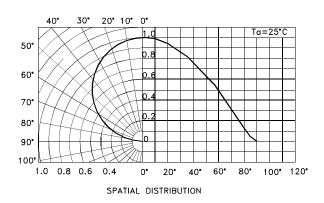
^{2. 1/10} Duty Cycle, 0.1ms Pulse Width.

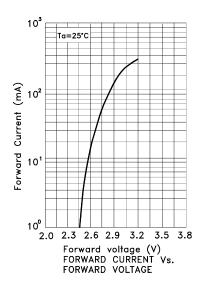
^{1.}Forward Voltage: + / -0.1V.

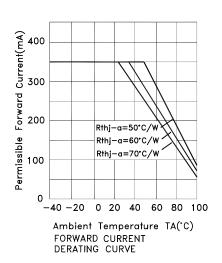
Kingbright

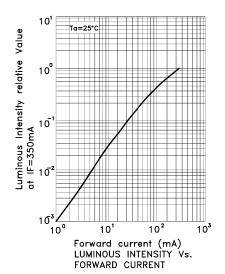


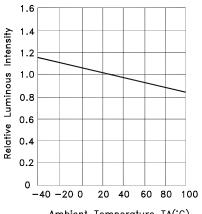
AT3535QR410ZS-RV-C1









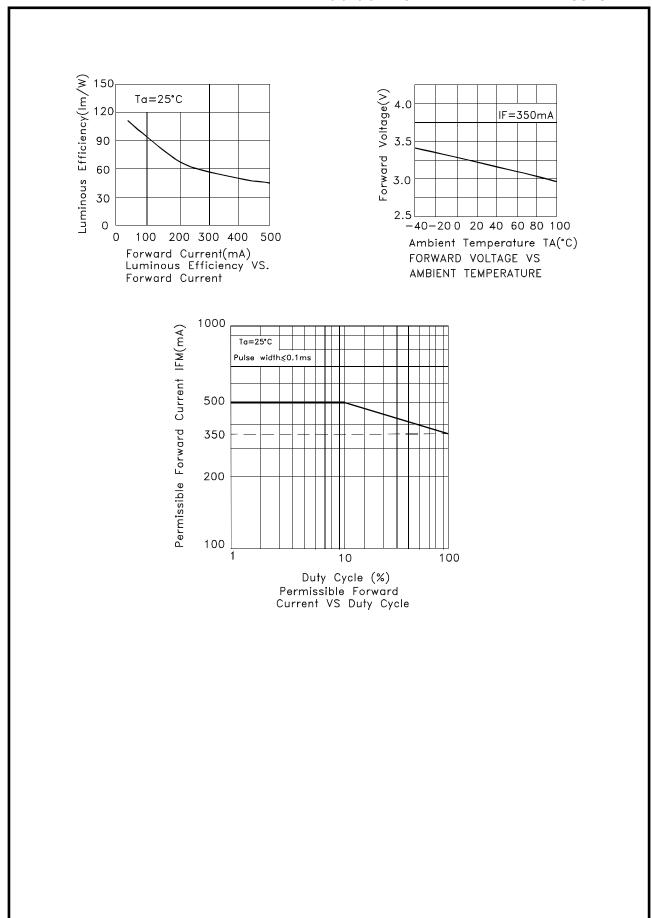


Ambient Temperature TA(°C) LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

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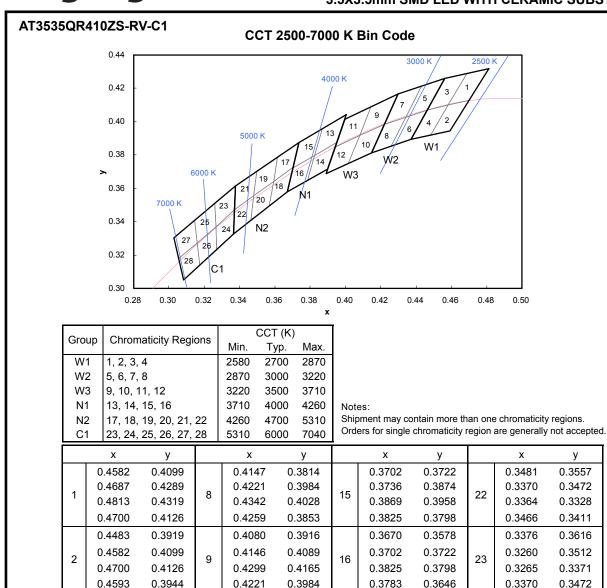




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		0.4582	0.4099		0.4147	0.3814		0.3702	0.3722		0.3481	0.3557
	4	0.4687	0.4289	8	0.4221	0.3984	45	0.3736	0.3874	22	0.3370	0.3472
	1	0.4813	0.4319	8	0.4342	0.4028	15	0.3869	0.3958	22	0.3364	0.3328
		0.4700	0.4126		0.4259	0.3853		0.3825	0.3798		0.3466	0.3411
Ī		0.4483	0.3919		0.4080	0.3916		0.3670	0.3578		0.3376	0.3616
	2	0.4582	0.4099	9	0.4146	0.4089	16	0.3702	0.3722	23	0.3260	0.3512
	_	0.4700	0.4126	9	0.4299	0.4165	10	0.3825	0.3798	23	0.3265	0.3371
		0.4593	0.3944		0.4221	0.3984		0.3783	0.3646		0.3370	0.3472
		0.4465	0.4071		0.4017	0.3751		0.3736	0.3874		0.3370	0.3472
	3	0.4562	0.4260	10	0.4080	0.3916	17	0.3616	0.3788	24	0.3265	0.3371
	٦	0.4687	0.4289	10	0.4221	0.3984	17	0.3592	0.3641	24	0.3270	0.3230
L		0.4582	0.4099		0.4147	0.3814		0.3703	0.3726		0.3364	0.3328
		0.4373	0.3893		0.3941	0.3848		0.3703	0.3726		0.3260	0.3512
	4	0.4465	0.4071	11	0.3996	0.4015	18	0.3592	0.3641	25	0.3144	0.3408
	7	0.4582	0.4099	' '	0.4146	0.4089	10	0.3568	0.3495	23	0.3160	0.3274
		0.4483	0.3919		0.4080	0.3916		0.3670	0.3578		0.3265	0.3371
		0.4342	0.4028		0.3889	0.3690		0.3616	0.3788		0.3265	0.3371
	5	0.4430	0.4212	12	0.3941	0.3848	19	0.3496	0.3702	26	0.3160	0.3274
	5	0.4562	0.4260	12	0.4080	0.3916	19	0.3481	0.3557	20	0.3175	0.3139
		0.4465	0.4071		0.4017	0.3751		0.3592	0.3641		0.3270	0.3230
ſ		0.4259	0.3853		0.3825	0.3798		0.3592	0.3641		0.3144	0.3408
	6	0.4342	0.4028	13	0.3869	0.3958	20	0.3481	0.3557	27	0.3028	0.3304
	6	0.4465	0.4071	13	0.4006	0.4044	20	0.3466	0.3411	21	0.3055	0.3177
		0.4373	0.3893		0.3950	0.3875		0.3568	0.3495		0.3160	0.3274
Ī		0.4221	0.3984		0.3783	0.3646		0.3496	0.3702		0.3160	0.3274
	_	0.4299	0.4165	1,1	0.3825	0.3798	24	0.3376	0.3616	20	0.3055	0.3177
	7	0.4430	0.4212	14	0.3950	0.3875	21	0.3370	0.3472	28	0.3081	0.3049
		0.4342	0.4028		0.3898	0.3716		0.3481	0.3557		0.3175	0.3139

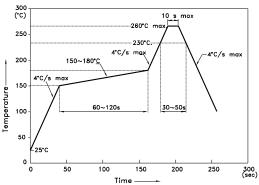
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

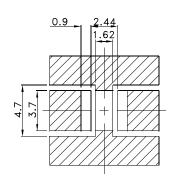


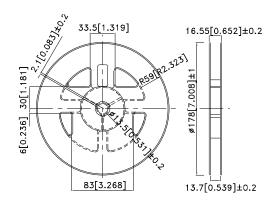
1.We recommend the reflow temperature $245^{\circ}C(+/-5^{\circ}C)$.The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units: mm; Tolerance: ± 0.1)

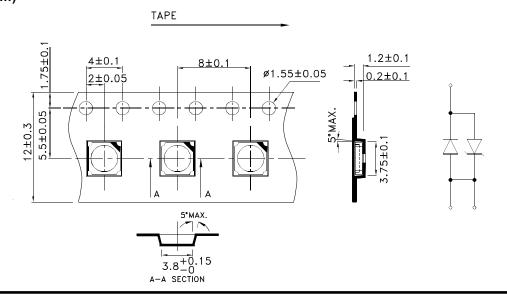
Reel Dimension





Solder resist

Tape Dimensions (Units: mm)

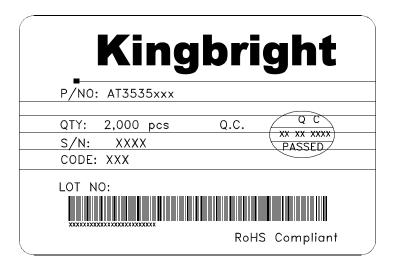


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Packing & Label Specifications AT3535QR410ZS-RV-C1 USER DIRECTION OF FEED LABEL-LABEL 2,000pcs / Reel 1Reel / Bag OUTSIDE LABEL OUTSIDE LABEL **Kingbright Kingbright** 30K / 55# Box 60K / 56# BOX



Packaging:

- 1. The LEDs are packed in cardboard boxes after taping.
- 2. The label on the minimum packing unit shows: Part Number, Lot Number, Ranking, Quantity.
- 3.In order to protect the LEDs from mechanical shock, we pack them in cardboard boxes for transportation.
- 4. The LEDs may be damaged if the boxes are dropped or receive a strong impact against them, so precautions must be taken to prevent any damage.
- 5. The boxes are not water resistant and therefore must be kept away from water and moisture.
- 6. When the LEDs are transported, we recommend that you use the same packing methods as Kingbright's.

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JEDEC Moisture Sensitivity:

Laval	Floor	l ife	Soak Requirements				
Level	/el Floor Life		Standard		Accelerated Equivalent		
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions	
2a	4 weeks	≤ 30 °C / 60% RH	696 ² + 5 / - 0	30 °C / 60% RH	120 + 1 / - 0	60 °C / 60% RH	

Notes:

- 1. CAUTION The "accelerated equivalent" soak requirements shall not be used until correlation of damage response, including electrical, after soak and reflow is established with the "standard" soak requirements or if the known activation energy for diffusion is 0.4 0.48 eV. Accelerated soak times may vary due to material properties, e.g., mold compound, encapsulant, etc. JEDEC document JESD22-A120 provides a method for determining the diffusion coefficient.
- 2. The standard soak time includes a default value of 24 hours for semiconductor manufacturer's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.

If the actual MET is less than 24 hours the soak time may be reduced. For soak conditions of 30 °C/60% RH the soak time is reduced by one hour For each hour the MET is less than 24 hours. For soak conditions of 60 °C/60% RH, the soak time is reduced by one hour for each five hours the MET is less than 24 hours.

If the actual MET is greater than 24 hours the soak time must be increased. If soak conditions are 30 °C/60% RH, the soak time is increased one Hour for each hour that the actual MET exceeds 24 hours. If soak conditions are 60 °C/60% RH, the soak time is increased one hour for each five Hours that the actual MET exceeds 24 hours.

3. Supplier may extend the soak times at their own risk.

ESD Protection During Production

Electric static discharge can result when static-sensitive products come in contact with the operator or other conductors.

The following procedures may decrease the possibility of ESD damage:

- 1. Minimize friction between the product and surroundings to avoid static buildup.
- 2.All production machinery and test instruments must be electrically grounded.
- 3. Operators must wear anti-static bracelets.
- 4. Wear anti-static suit when entering work areas with conductive machinery.
- 5.Set up ESD protection areas using grounded metal plating for component handling.
- 6.All workstations that handle IC and ESD-sensitive components must maintain an electrostatic potential of 150V or less.
- 7. Maintain a humidity level of 50% or higher in production areas.
- 8. Use anti-static packaging for transport and storage.
- 9.All anti-static equipment and procedures should be periodically inspected and evaluated for proper functionality.

Heat Generation:

- 1.Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board ,as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.
- 2.Please determine the operating current with consideration of the ambient temperature local to the LED and refer to the plot of Permissible Forward current vs. Ambient temperature on CHARACTERISTICS in this specification. Please also take meas ures to remove heat from the area near the LED to improve the operational characteristics on the LED.

3.The equation ①	indicates correlation betwe	n Tj and Ta, and the equation 2	indicates correlation b	etween Tj and Ts
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 $T_j = T_a + R_{thj-a} *W$ ① $T_j = T_s + R_{thj-s} *W$ ②

Tj = dice junction temperature: °C
Ta = ambient temperature: °C

Ts = solder point temperature: °C

Rthj-a = heat resistance from dice junction temperature to ambient temperature : °C/ W

Rthj-s = heat resistance from dice junction temperature to Ts measuring point : °C/ W

W = inputting power (IFx VF) : W

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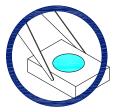


Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

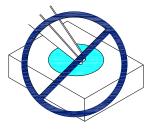
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

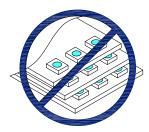


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

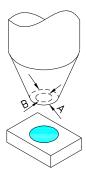




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



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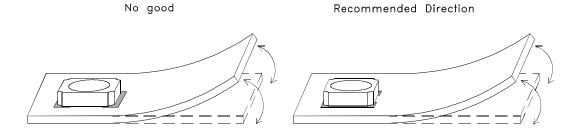
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Designing the Position of LED on a Board.

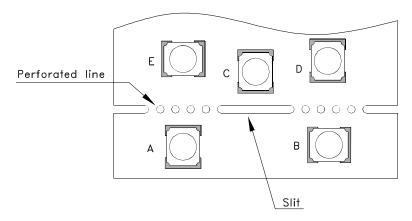
1.No twist/warp/bent/or other stress shall be applied to the board after mounting LED with solder to avoid a crack of LED package.

Refer to the following recommended position and direction of LED.



Appropriate LED mounting is to place perpendicularly against the stress affected side.

2.Depending on the position and direction of LED,the mechanical stress on the LED package can be changed. Refer to the following figure.



Stress: A>B=C>D>E

- 3.Do not split board by hand. Split with exclusive special tool.
- ${\it 4.} If an aluminum circuit board is used, a large stress by thermal shock might cause a solder crack.\\$

For this reason, it is recommended an appropriate verification should be taken before use.

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Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below

Lot Tolerance Percent Defective (LTPD): 10%

No.	Test Item	Test Conditions	Test Times / Cycles	Number of Damaged
1	Continuous Operating Test	T_a = 25 °C , I_F = 350 mA Tested with standard circuit board [*]	1000 hrs	0/22
2	High Temperature Operating Test	T _a = 100 °C , I _F = 60 mA (note)	1000 hrs	0/22
3	Low Temperature Operating Test	T_a = -40 °C , I_F = 350 mA Tested with standard circuit board	1000 hrs	0/22
4	High Temperature and Humidity Storage Operating Test	T _a = 85 °C , RH = 85% , I _F = 110 mA (note)	1000 hrs	0/22
5	Temperature Cycling Test	High temp: +100 °C 30 mins R.T: 5 mins Low temp: -40 °C 30 mins R.T: 5 mins	10 cycles	0/22
6	Thermal Shock Test	High temp: +100 °C 5 mins Low temp: -40 °C 5 mins	1000 cycles	0/22
7	Soldering resistance Test	T _{sld} = 260 °C , 10 secs	10 secs	0/22

Note: Thermal resistance of LED with Kingbright circuit board: Rthj-a =70°C/W

Failure Criteria

Item	Symbol	Test Conditions	Criteria for Judgement		
	-		Min.	Max.	
Forward Voltage	VF	IF = 350mA	-	Initial Level x 1.1	
Luminous Flux	Ф۷	IF = 350mA	Initial Level x 0.7	-	

Note: The test is performed after the board is cooled down to the room temperature.

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